© Copyrigh	l Composition De ht 2005. IPC, Bannock al and Pan-American c	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, th	ent is a declarat he declaration e	ion of the su encompasses	ibstances v s all lower	within the manufacture level materials for w	rer listed ite hich the ma	em. Note: i anufacture	if the item is an as r has engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information													
Company name* Company unique ID					1	Unique ID Authority				Response Date*			
nsemi									2023-06-08				
Contact Name Tit			Title - Contact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - I			presentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Prod			ct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iten		n Number Mfr Item Name		·	Effective Date	ate Version Manufacturing Site		v	/eight*	UOM	Unit Type		
	LC8234	C823460RAH-2H Portable Sound Solu		olutions		2023-06-08	РНМ		3	7.26	mg	Each	
Ianufacturing Proccess Ir	nformation												
Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MS	TD-020 MSL Rating Pe		Peak Process Body Temperature Max Time at Peal		Temperatu	re Numl	ber of Reflow Cyc	eles		
SnAgCu CU Alloy			3		260		С	30	second	s 3			
omments													
TTENTION: MSL 3 Rated item	n requires Bake and I	Dry Pack (after	electrical test)										
or more information regarding	material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitors Ceramic	0.33	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.066	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.002	mg
			Supplier	Tin (Sn)	7440-31-5		0.019	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.006	mg
			Supplier	Misc.	Proprietary Data		0.023	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.132	mg
			В	Nickel (Ni)	7440-02-0		0.015	mg
			Supplier	Copper (Cu)	7440-50-8		0.067	mg
Die	2.4	mg	Supplier	Silicon (Si)	7440-21-3		2.4	mg
Die Attach	2.8	mg		Butadiene Copolymer	proprietary data		0.42	mg
			Supplier	Antimony Compound	Proprietary Data		0.042	mg
			Supplier	Peroxide	Proprietary Data		0.028	mg
			Supplier	Methacrylate	Proprietary Data		0.672	mg
			Supplier	Other Additive Agents	Proprietary Data		0.028	mg
			Supplier	Inorganic filler	Proprietary Data		0.112	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.868	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.574	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.056	mg
Mold Compound-Black	2.01	mg		Epoxy resin	proprietary data		0.1106	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1106	mg
			Supplier	Carbon Black (C)	1333-86-4		0.006	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.7829	mg
Solder Ball	7.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0888	mg
			Supplier	Tin (Sn)	7440-31-5		7.2002	mg
			Supplier	Copper (Cu)	7440-50-8		0.111	mg
Substrate and Solder Mask	3.0	mg	Supplier	Gold Potassium Cyanide	13967-50-5		0.159	mg
			Supplier	Talc	14807-96-6		0.0492	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		0.336	mg
			Supplier	Naphthalene	91-20-3		0.018	mg
			Supplier	Morpholine derivative	Proprietary Data		0.132	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		0.1497	mg
			Supplier	Inorganic filler	Proprietary Data		0.1413	mg

			В	Nickel (Ni)	7440-02-0	0.4674	mg
			Supplier	Copper (Cu)	7440-50-8	1.185	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.3624	mg
Wire Bond - Au	19.32	mg	Supplier	Gold (Au)	7440-57-5	19.32	mg